

REMARKS

Favorable reconsideration of this application is respectfully requested in view of the previous amendments and the following remarks.

Independent Claim 15, is again rejected based on the disclosures in U.S. Patent No. 6,744,634, hereinafter Yen, and U.S. Patent No. 6,159,770, hereinafter Tetaka.

In the Official Action, the Examiner asserts that the resin packages and 412 and gates 432 illustrated in Fig. 173A of Tetaka constitute a tape, that separating the resin packages 412 from the gates 432 constitute cutting a microcircuit from a tape, and that fabricating Yen's printed circuit boards 202 by cutting them out from a tape would therefore have been obvious to an ordinarily skilled artisan. Applicants respectfully disagree.

As a first point, it is quite clear Yen's printed circuit boards 202 are rigid structures very different from Tetaka's resin packages 412 or a microcircuit carried on a tape. Applicants respectfully submit that it is not possible to cut a rigid printed circuit board from a tape.

Moreover, Claim 15 is amended to recite cutting out, from a dielectric backing film which has a thickness of less than or equal to 200 μm and carries a plurality of microcircuits, a portion of the dielectric backing film including one of the microcircuits. Neither Yen nor Tetaka disclose a dielectric backing film which has a thickness of less than or equal to 200 μm , much less cutting out a portion of such a dielectric backing film including a microcircuit.

Finally, Yen does not disclose, in a single operation, increasing the thickness of a dielectric backing film including a microcircuit at least in the area of contact pads

of the microcircuit, so as to have a thickness that conforms to the USB Standard.

Indeed, in Yen, each USB key is made on a different PCB, which would therefore require electronic components such as those of Tetaka to be soldered on the PCB.

In light of the foregoing, Applicants respectfully submit that amended Claim 15 is clearly distinguishable from the disclosures in Yen and Tetaka. Withdrawal of the rejection of Claim 15 is therefore respectfully requested.

New Claim 16, which recites a method for manufacturing a USB electronic key from a dielectric backing film which has a thickness of less than or equal to 200 μm and carries a microcircuit, the microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, the method comprising, in a single operation, increasing the thickness of the dielectric backing film including the microcircuit at least in the area of the contact pads of the microcircuit, so as to have a thickness that conforms to the USB Standard, is also allowable over the disclosures in Yen and Tetaka.

For example, as discussed above with respect to Claim 15, neither Yen nor Tetaka disclose a dielectric backing film which has a thickness of less than or equal to 200 μm , or, in a single operation, increasing the thickness of a dielectric backing film including a microcircuit at least in the area of contact pads of the microcircuit, so as to have a thickness that conforms to the USB Standard.

The dependent claims are allowable at least by virtue of their dependence from allowable independent claims. Thus, a detailed discussion of the additional distinguishing features recited in the dependent claims is not set forth at this time.

Early and favorable action with respect to this application is respectfully requested.

Should any questions arise in connection with this application or should the Examiner believe that a telephone conference with the undersigned would be helpful in resolving any remaining issues pertaining to this application, the undersigned respectfully requests that he be contacted at the number indicated below.

The Director is hereby authorized to charge any appropriate fees under 37 C.F.R. §§ 1.16, 1.17 and 1.20(d) and 1.21 that may be required by this paper, and to credit any overpayment, to Deposit Account No. 02-4800.

Respectfully submitted,

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